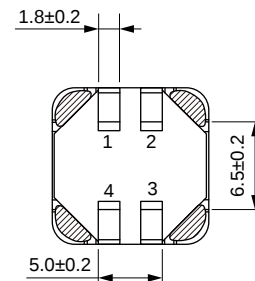
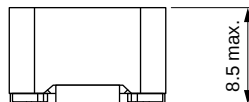
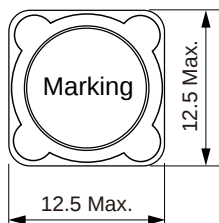


SMD Shielded Power Inductor Size 1280

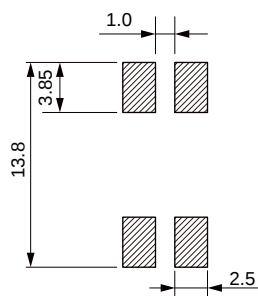


- Low loss realized with low DCR.
- High performance realized by metal dust core.
- 100% Lead(Pb)-Free and RoHS compliant.
-
-
-
- HVAC
-
- Audio subsystem
- Digital instrument cluster
-
- SEPIC circuit

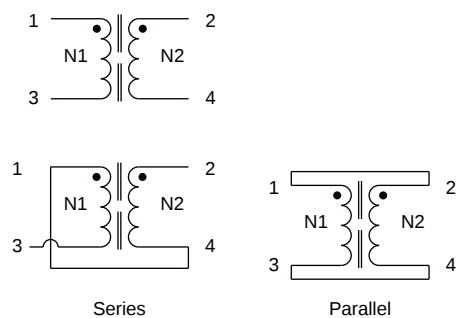
Dimensions: [mm]



Land Patterns: [mm]



Schematic:



Electrical Properties:

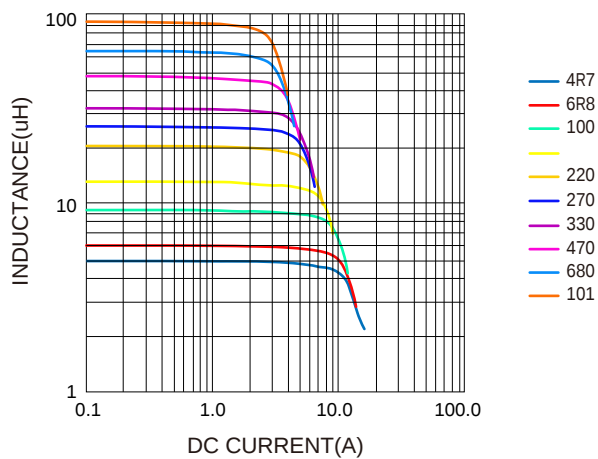
Part No	Inductance @ 100KHz/0.1V (μ H)	Tolerance	Temperature Rise Current Typ. (A)	Satura on Current Typ. (A)	Satura on Current Max. (A)	DC Resistance Max. (m Ω)	Hi-POT
SDDA1280-4R7M	4.7	$\pm 20\%$		12.9	9.2		
SDDA1280-6R8M	6.8	$\pm 20\%$		11.4	8.1	29	
SDDA1280-100M	10	$\pm 20\%$	4.1	9.8	6.8	36	
		$\pm 20\%$	3.6	7.0		40	
SDDA1280-220M	22	$\pm 20\%$	3.0	6.7	4.7	72	
SDDA1280-270M	27	$\pm 20\%$	2.7		3.9	96	
SDDA1280-330M	33	$\pm 20\%$			3.6		
SDDA1280-470M	47	$\pm 20\%$	2.2	4.3	3.1	132	
SDDA1280-680M	68	$\pm 20\%$	1.8	3.6		206	
SDDA1280-101M	100	$\pm 20\%$		3.0	2.1	280	

Saturation Current will cause L to drop approximately 30%

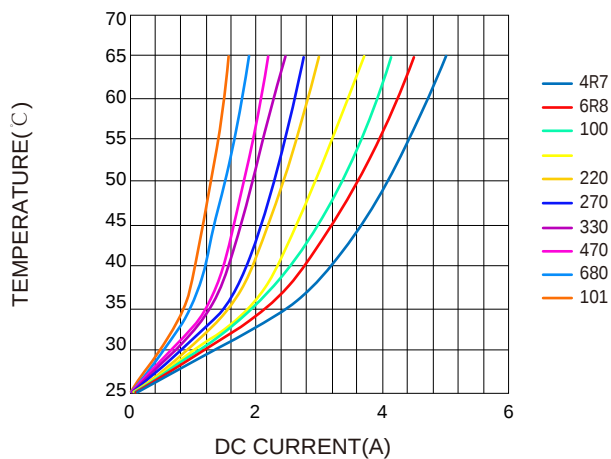
Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T = 40^\circ\text{C}$

Typical Electrical Characteristics:

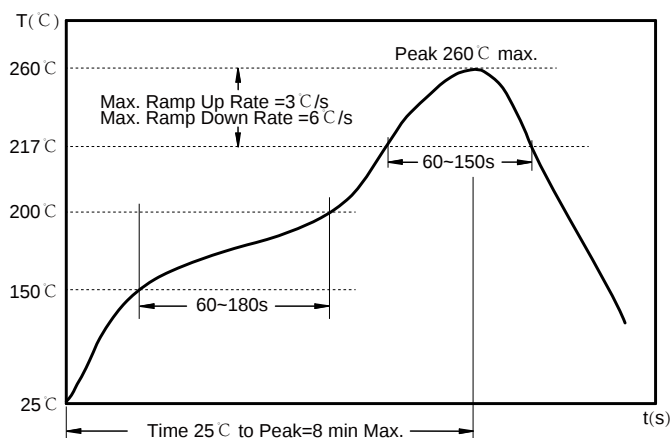
Inductance VS. DC Current Characteristics:



Temperature VS. DC Current Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200°C / 60~180 sec.

Allowed time above 217°C : 60~150 sec.

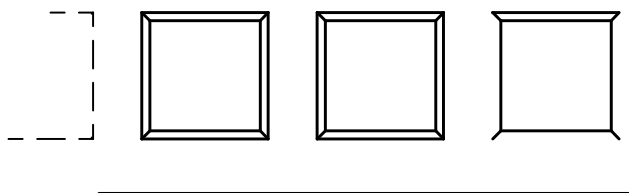
Max temperature: 260°C.

Max time at max temperature: 5 sec.

Allowed Reflow time: 3x max.

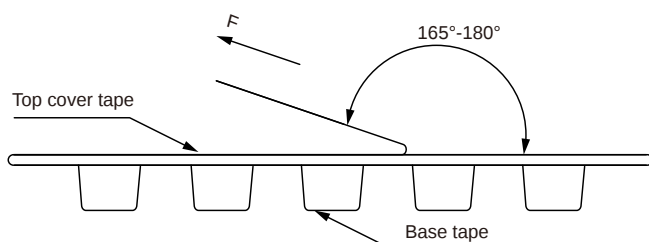
Packaging Information:

Tape Dimension:



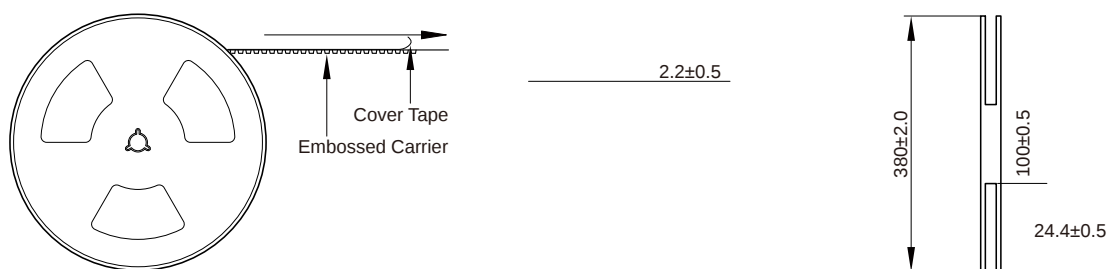
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
SDDA1280	12.5±0.1	12.5±0.1	1.5±0.1	4.0±0.1	20.0±0.1	24.0±0.3	8.4±0.1	1.75±0.1	0.50±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Reel Dimension: [mm]



Packaging Quantity:

500 Pcs/Reel

2 Reel /Inner box(1000 Pcs)